L Number	Hits	Search Text	DB	Time stamp
1	87	stack near4 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 09:31
2	6	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 10:14
3	5	<pre>(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic or spacer) near12 (insulat\$3 or isolat\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 10:15
8	29	riser near6 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:04
9	2	riser near10 heat adj sink near10 (liquid or flow or fluid or coolant or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:05
10	28	riser nearl0 (liquid or flow or fluid or coolant or water) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:53
13	2	("5794839").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 13:19
14	7	semiconductor adj laser.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 14:10
. 15	1	heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink and (upper adj electrode near20 lower adj electrode)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 14:08
16	2	semiconductor.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) adj heat adj "sinks" and (top upper) adj electrode	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 14:22
20	36		USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 14:28
21	9		IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 15:21
23	174	257/625	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 16:09

24	8124	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:23
26	1	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (riser guide guiding) nearl2 (flow liquid water coolant) and (stack stacked) near2 heat	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:13
27	2	adj sink (((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and stacked adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:39
28		(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13
32	0	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13
33	2	and (first upper top) adj electrode ((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13
34	0	and electrode stacked adj heat adj sinks.ti,ab,clm. and semiconductor adj2 (element device) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13
35	4	<pre>(stack stacking stacked) near12 heat adj sinks and semiconductor adj2 (element device) and ((top upper) adj electrode)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 19:31
36	2	("4631573").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13
37	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 17:31
38	1	stacked.ti,ab,clm. and heat adj sink.ti,ab,clm. and (electronic or semiconductor) adj (device or element) and "in series"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 19:34
39	0	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and "in series"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 19:35
40	74	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and series	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 19:53

41	•	8	stacked near3 active near3 region near3 monolithic near3 laser near3 array	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003705713 19:55	
42		2	("5157680").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 19:55	
43		20	stacked nearl2 active nearl2 laser nearl2 array	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 20:35	
44		2	("4791634").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13	
. 45		2	· ·	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13 21:08	1
46	I	0	("jp-8181392\$-\$.did.").PN.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13 21:09	1
47		2	jp-08181392\$-\$.did.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/05/13	i
48	!		bell.in. and morrison.in. and law.in. and malcolm.in.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/05/13	
49	1	1	gb-1597829\$-\$.did.	EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/13	
_	i	2	jp-09102568\$-\$.did.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/13	
]	į			US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	- 09:31	Ĩ
-	1	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/06	
_		2	jp-08139479\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/06 16:24	
-		3	("5785754").PN.	IBM_TDB USPAT; US-PGPUB; EPO, JPO, DERWENT;	2002/08/06 16:24	
-		2008	((372/34) or (372/35) or (372/36)).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/23 15:24	
				DERWENT; IBM_TDB		

	996	heat adj sink.ti. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/07 07:45
-	33	heat adj sink.ti. and liquid.ti,ab. and 257/\$6.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 15:28
-	20	((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and laser.ti,ab. and heat adj sink.ti,ab. and (liquid or water).ti,ab.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 08:27
- )	8	(US-6307871-\$ or US-5801442-\$ or US-4791634-\$ or US-4712609-\$ or US-3764935-\$).did. or	USPAT; US-PGPUB; JPO	2002/08/07
		(US-20010004370-\$).did. or (JP-02257683-\$) or JP-63073584-\$).did.		
-	388	(257/365).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/08
- !	6068	(((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:50
-	307	(((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09
-	110	(((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:53
-	63	coolant)) and (groove or slit or trench) ((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:55
_	40	and (stack or (upper near12 lower)) (((((((372/34) or (372/35) or (372/36)).CCLS.)) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and	USPAT	2002/08/09 12:56
_	1.4	<pre>(liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor</pre>	1	i i
_		((((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near& (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper nearl2 lower))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_IDB	2002/08/09 13:32
-	1	heat adj sink.ti. and liquid.ti,ab. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:29

2	33	heat adj sink.ti. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 15:29
			IBM_TDB	
-	10026	heat adj sink and upper nearl2 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 11:24
-	710	heat adj sink.ti. and upper near12 lower	IBM_TDB USPAT; US-PGPUB;	2002/08/23 11:25
			EPO; JPO; DERWENT; IBM TDB	
-	70	heat adj sink.ti. and upper near12 lower near12 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23
*			IBM TDB	
	30	heat adj sink.ti. and upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23
-	2	heat adj sink.ti. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/23
			DERWENT; IBM_TDB	
	2	heat adj sink.ti,ab. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23
-	2	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower adj (face or main adj surface)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 11:35
-	4	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower near6 (face or main adj surface)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 11:52
-	6	heat adj sink.ti,ab. and (groove or trench) near18 ((upper near18 lower) near18 (face or main adj surface))	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/23
			DERWENT; IBM TDB	
=	4163	((257/712) or (257/713) or (257/714) or (257/715)).CcLs.	USPAT; US-PGPUB; EPO; JPO;	2002/08/23 14:08
<u>.</u>			DERWENT;	1
_	1156	(372/34).CCLS.	IBM_TDB USPAT;	2002/08/23
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB; EPO; JPO;	15:25
			DERWENT;	i
-	423	(372/35).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 15:25
-	661	(372/36).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 15:26

	1884	(257/712).CCLS.	USPAT; US-PGPUB; EPO; JPO;	2002/08/23 15:26
			DERWENT;	
			IBM_TDB	
_	958	(257/713).CCLS.	USPAT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO;	
			DERWENT;	
	1102	(257/714)	IBM_TDB	0000 /00 /00
_	1193	(257/714).CCLS.	USPAT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO; DERWENT;	
			IBM TDB	
· -	493	(257/715).CCLS.	USPAT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO;	
			DERWENT;	
I.	C1 4 4	(/270/24)	IBM_TDB	
- ;	6144	((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
1		((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or	US-PGPUB;	15:27
		((257/715).CCLS.) OF ((257/714).CCLS.) OF	EPO; JPO; DERWENT;	
		((23)) (13) (6813.)	IBM TDB	
	4269	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:28
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	
		((257/715).CCLS.)) and (heat adj removal	DERWENT;	
	25.00	or heat adj sink or coolant or cooling)	IBM_TDB	
-	3590	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or	US-PGPUB;	15:29
		((257/715).CCLS.)) and (heat adj removal	EPO; JPO; DERWENT;	
		or heat adj sink or coolant or	IBM TDB	123
		cooling).ti,ab,clm.	1211_122	1
* -	1280	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	; 2002/08/23
1		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:29
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	
		((257/715).CCLS.)) and (heat adj removal	DERWENT;	
		or heat adj sink or coolant or cooling).ti,ab,clm. and liquid	IBM_TDB	
_	263	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:30
- '		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	
1			DERWENT;	T T
		or heat adj sink or coolant or	IBM_TDB	
		cooling).ti,ab,clm. and liquid and		
_	27	(groove or trench)   (US-6198758-\$ or US-6310900-\$ or	IICDam.	2002 (00 (22
	2 /		USPAT; US-PGPUB;	2002/08/23 18:39
			JPO;	10.39
· ·		US-5864176-\$ or US-5918665-\$ or	DERWENT	
		US-6157077-\$ or US-6274912-\$ or		
		US-6347050-\$ or US-5801442-\$ or	i i	İ
		US-4712609-\$ or US-3764935-\$ or		1
		US-5241450-\$ or US-4791634-\$ or		Ť
		US-5812570-\$ or US-6307871-\$).did. or		
		(US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or		
		JP-08227953-\$ or JP-08139479-\$).did. or		
		(JP-09102568-\$ or EP-715352-\$ or		
		JP-00139479-\$).did.		

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5 ((US-6198758-$ or US-6310900-$ or
                                                   USPAT;
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     US-3654528-$ or US-4807022-$ or
                                                   US-PGPUB;
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     US-5729052-$ or US-5783862-$ or
                                                   EPO; JPO;
     US-5864176-$ or US-5918665-$ or
                                                   DERWENT;
     US-6157077-$ or US-6274912-$ or
                                                   IBM TDB
     US-6347050-$ or US-5801442-$ or
     US-4712609-$ or US-3764935-$ or
     US-5241450-$ or US-4791634-$ or
     US-5812570-$ or US-6307871-$).did. or
     (US-20010004370-\$).did. or (JP-02257683-\$)
     or JP-63073584-$ or JP-09102568-$ or
     JP-08227953-\$ or JP-08139479-\$).did. or
     (JP-09102568-\$ or EP-715352-\$ or
     JP-08139479-$).did.) and laser adj diode
  2 ("4791634").PN.
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  2 jp-08227953$-$.did.
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     zengerle.in. and heat
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                                                               2002/08/24
                                                  US-PGPUB;
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                                                  EPO; JPO;
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  4 zengerle.in. and power adj semiconductor
                                                  USPAT;
                                                               2002/08/24
     adj component
                                                  US-PGPUB;
                                                               15:26
                                                  EPO; JPO;
                                                  DERWENT;
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  4 | 773510.ap.
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                                                               2003/05/10
                                                  US-PGPUB;
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                                                  EPO; JPO;
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127 (((372/43) or (372/44) or (372/45) or
                                                  USPAT:
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     (372/46) or (372/47) or (372/48) or
                                                  US-PGPUB;
                                                               15:18
     (372/49) or (372/50) or (372/34) or
                                                  EPO; JPO;
     (372/35) or (372/36) or (257/712) or
                                                  DERWENT:
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     (257/715)).CCLS.) and heat adj
     sink.ti, ab, clm. and semiconductor adj
     laser and (coolant or water or fluid or
    flow)
103 + (((372/43) \text{ or } (372/44) \text{ or } (372/45) \text{ or }
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     (372/46) or (372/47) or (372/48) or
                                                  EPO; JPO;
     (372/49) or (372/50) or (372/34) or
                                                  DERWENT;
     (372/35) or (372/36) or (257/712) or
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     (257/713) or (257/714) or
     (257/715)).CCLS.) and heat adj
     sink.ti, ab, clm. and semiconductor adi
     laser and (coolant or water or fluid or
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103 (((372/43) or (372/44) or (372/45) or
                                                  USPAL;
                                                              2003/05/10
     (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or
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                                                  DERWENT;
     (372/35) or (372/36) or (257/712) or
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     (257/713) or (257/714) or
     (257/715)).CCLS.) and heat adj
    sink.ti,ab,clm. and semiconductor adj
    laser and (coolant or water or fluid or
   flow) and heat adj sink.ti,ab,clm.
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2 ****	4	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/49) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:32
-	5	adj sink (((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:48
		laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink		
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/10
_	1627	(257/678).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
_	36	((257/678).CCLS.) and heat adj sink.ti,ab,clm. and (liquid or water or flow or coolant)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:39
-	109	hayashi.in. and heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:40
-	18	hayashi.in. and laser.ti,ab,clm. and heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:42
-	2	jp-09102568\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	1442	heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	3	lsi and (heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 13:59
-	2	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:00
-	4	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:09

	491	semiconductor adj laser near6 heat adj sink.tı,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 14:09
-	249	semiconductor adj laser near3 heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 14:11
-	1	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and liquid adj coolant	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 14:12
-	35	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	2	jp-08227953\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	2	("3351698").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/12 15:22
-	0	("heat adj sink near20 laser near20 electrode near20 copper").PN.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:22
-	19	heat adj sink near20 laser near20 electrode near20 copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:53
-	0	top adj electrode nearl2 bottom adj electrode near20 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	44	"electrodes" near12 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:56
-	29	"electrodes" near6 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
	8	"electrodes" near3 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:02
-	4	773510.ap.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	2118	heat adj sink nearl2 electrode	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:07

	4	773510.ap.	USPAT; US-PGPUB;	2003/05/12 19:18
			EPO; JPO; DERWENT; IBM TDB	
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:34
-	2	guiding adj (hole or through-hole or aperture) near12 heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:51
-	115	(hole or through-hole or aperture) near12 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or	<pre>IBM_TDB USPAT;</pre>	2003/05/12
* -	103	(hole or through-hole or aperture) near6	DERWENT; IBM_TDB	2002/05/22
	103	(guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
_	57	(hole or through-hole or aperture) near3 (guide or guiding) and heat adj	IBM_TDB USPAT; US-PGPUB;	2003/05/12 19:56
	3	sink.ti,ab,clm. and (liquid or water or coolant) (hole or through-hole or aperture) near3	EPO; JPO; DERWENT; IBM_TDB	
		(guide or guiding) near12 heat adj sink near12 (liquid or water or coolant) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:59
† †	2	jp-09102568\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/12
-	2	jp-08227953 <b>\$-\$</b> .did.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 20:01
-	3	("5785754").PN.	IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB	2003/05/12 20:30
-	0	("heat adj sink near12 (leak or leakage or leaking) near12 rubber").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 20:30
-	0	heat adj sink near12 (leak or leakage or leakıng) near12 rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 20:31
-	0	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber)	USPAT; US-PGPUB; DFO, JFO, DERWENT; IBM TDB	2003/05/12 20:32
_	20	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber insulating insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 21:09

2 jp-08181392\$-\$.did. USPAT; 2003/05/12 US-PGPUB; 21:09 EPO; JPO; DERWENT; IBM\_TDB